

RAD-TOLERANT CLASS V, BRUSHLESS DC MOTOR CONTROLLER

Check for Samples: UC1625-SP

FEATURES

- QML-V Qualified, SMD 5962-91689
- Rad-Tolerant: 40 kRad (Si) TID (1)
- Drives Power MOSFETs or Power Darlingtons Directly
- 50-V Open Collector High-Side Drivers
- · Latched Soft Start
- Radiation tolerance is a typical value based upon initial device qualification with dose rate = 10 mrad/sec. Radiation Lot Acceptance Testing is available - contact factory for detials.

- High-speed Current-Sense Amplifier with Ideal Diode
- Pulse-by-Pulse and Average Current Sensing
- Over-Voltage and Under-Voltage Protection
- Direction Latch for Safe Direction Reversal
- Tachometer
- Trimmed Reference Sources 30 mA
- Programmable Cross-Conduction Protection
- Two-Quadrant and Four-Quadrant Operation

DESCRIPTION/ORDERING INFORMATION

The UC1625 motor controller integrates most of the functions required for high-performance brushless dc motor control into one package. When coupled with external power MOSFETs or Darlingtons, this device performs fixed-frequency PWM motor control in either voltage or current mode while implementing closed loop speed control and braking with smart noise rejection, safe direction reversal, and cross-conduction protection.

Although specified for operation from power supplies between 10 V and 18 V, the UC1625 can control higher voltage power devices with external level-shifting components. The UC1625 contains fast, high-current push-pull drivers for low-side power devices and 50-V open-collector outputs for high-side power devices or level shifting circuitry.

The UC1625 is characterized for operation over the military temperature range of –55°C to 125°C.

ORDERING INFORMATION(1)

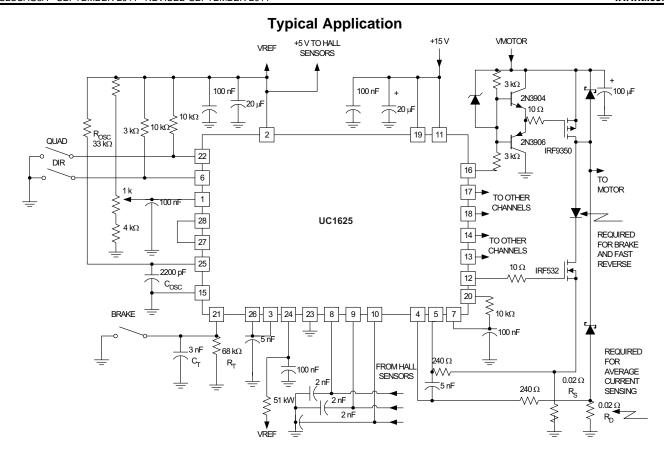
T _A	PACKAGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	CDIP – JT	5962-9168902VYA	5962-9168902VYA UC1625-SP

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





ABSOLUTE MAXIMUM RATINGS(1) (2)

over operating free-air temperature range (unless otherwise noted)

		VALUE	UNIT
VCC	0 1 1	20	
PWR VCC	Supply voltage	20	
	PWM IN	-0.3 to 6	
	E/A IN(+), E/A IN(-)	-0.3 to 12	V
	ISENSE1, ISENSE2	-1.3 to 6	V
	OV-COAST, DIR, SPEED-IN, SSTART, QUAD SEL	-0.3 to 8	
	H1, H2, H3	-0.3 to 12	
	PU Output Voltage	-0.3 to 50	
PU		+200 continuous	
PD		±200 continuous	
E/A	Output surrent	±10	Л
I _{SENSE}	Output current	-10	mA
TACH OUT		±10	
VREF		-50 continuous	
TJ	Maximum Junction Temperature	150	°C

¹⁾ Currents are positive into and negative out of the specified terminal.

Submit Documentation Feedback

Copyright © 2011, Texas Instruments Incorporated

⁽²⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only and functional operation of the device at these or any other conditions beyond those specified is not implied.



RECOMMENDED OPERATING CONDITIONS

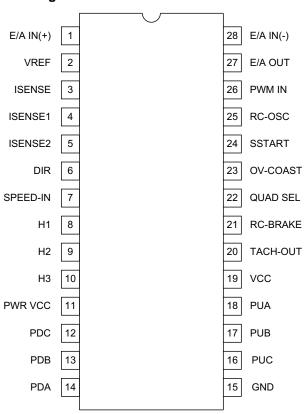
over operating temperature range (unless otherwise noted)

		MIN	NOM I	ΛΑN	UNIT
V _{CC}	Supply Voltage	10		18	V
PU	Output Current		continu	+85 Jous	mA
PD			continu	±85 Jous	mA
T _A	Operating temperature range	-55		125	°C

Table 1. THERMAL RATINGS TABLE

PACKAGE	R _{θJA} (°C/W) (Junction-to-ambient thermal resistance)	R _{θJC} (°C/W) (Junction-to-case thermal resistance)
DIL-28 (JT)	43.1	4.95

Figure 1. CONNECTION DIAGRAM



Copyright © 2011, Texas Instruments Incorporated



ELECTRICAL CHARACTERISTICS

Unless otherwise stated, these specifications apply over the full temperature range, typical values at $T_A = 25$ °C; Pwr $V_{CC} = V_{CC} = 12$ V; $R_{OSC} = 20$ k Ω to V_{REF} ; $R_{COSC} = 20$ nF; $R_{TACH} = 33$ k Ω ; $R_{TACH} = 10$ nF; and all outputs unloaded. $R_{TACH} = 10$ nF; and all outputs unloaded.

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Overall					\ldots	
	Supply current			14.5	30.0	mA
	VCC turn-on threshold	-55°C to 125°C	8.65	8.95	9.55	
	VCC turn-off threshold		7.75	8.05	8.55	V
Overvolt	tage/Coast					
	OV-COAST inhibit threshold		1.65	1.75	1.85	
	OV-COAST restart threshold		1.535	1.65	1.75	V
	OV-COAST hysteresis	-55°C to 125°C	0.05	0.10	0.155	
	OV-COAST input current		-10	-1	10	μA
Logic In	· · · · · · · · · · · · · · · · · · ·					
	H1, H2, H3 low threshold		0.8	1.0	1.25	
	H1, H2, H3 high threshold	-55°C to 125°C	1.6	1.9	2.0	V
	H1, H2, H3 input current	-55°C to 125°C, to 0 V	-400	-250	-120	μA
	QUAD SEL, dir thresholds	,	0.8	1.4	3.0	V
	QUAD SEL hysteresis	_		70	130	mV
	DIR hysteresis	-55°C to 125°C	0.4	0.6	0.9	V
	QUAD SEL input current		-30	50	150	
	DIR input current	=	-30	-1	30	μΑ
PWM An	np/Comparator					
	E/A IN(+), E/A IN(-) input current	To 2.5 V	-5.0	-0.1	5.0	
	PWM IN input current	To 2.5 V	0	3	30	μΑ
	Error amp input offset	0 V < V _{COMMON-MODE} < 3 V	-10		10	mV
	Error amp voltage gain	- CONTROL -	70	90		dB
	E/A OUT range	25°C to 125°C	0.25		3.50	
	3	-55°C	0.25		4.2	V
	Pullup current	To 0 V, 25°C	-16	-10	-5	
		To 0 V , -55°C to 125°C	-17.5		-5	μΑ
S _{START}	Discharge current	To 2.5 V	0.1	0.4	3.0	mA
	Restart threshold		0.1	0.2	0.3	V
Current						
	Gain	I _{SENSE1} = 0.3 V, I _{SENSE2} = 0.5 V to 0.7 V	1.75	1.95	2.15	V/V
	Level shift	I _{SENSE1} = 0.3 V, I _{SENSE2} = 0.3 V	2.4	2.5	2.65	
	Peak current threshold		0.14	0.20	0.26	V
	Over current threshold	I _{SENSE1} = 0 V, force I _{SENSE2}	0.26	0.30	0.36	
	I _{SENSE1} , I _{SENSE2} input current		-850	-320	0	
	I _{SENSE1} , I _{SENSE2} offset current	To 0 V	-12	±2	12	μΑ
	Range I _{SENSE1} , I _{SENSE2}		-1		2	V
Tachom	eter/Brake	1				
	TACH-OUT high level		4.7	5	5.3	
	TACH-OUT low level	-55°C to 125°C, 10 kΩ to 2.5 V			0.2	V
	On time		170	220	280	μs
	On time change with temp	-55°C to 125°C		0.1%		F
	RC-BRAKE input current	To 0 V	-4.0	-1.9		mA



ELECTRICAL CHARACTERISTICS (continued)

Unless otherwise stated, these specifications apply over the full temperature range, typical values at T_A = 25°C; Pwr V_{CC} = V_{CC} = 12 V; R_{OSC} = 20 k Ω to V_{REF} ; C_{OSC} = 2 nF; R_{TACH} = 33 k Ω ; C_{TACH} = 10 nF; and all outputs unloaded. T_A = T_J .

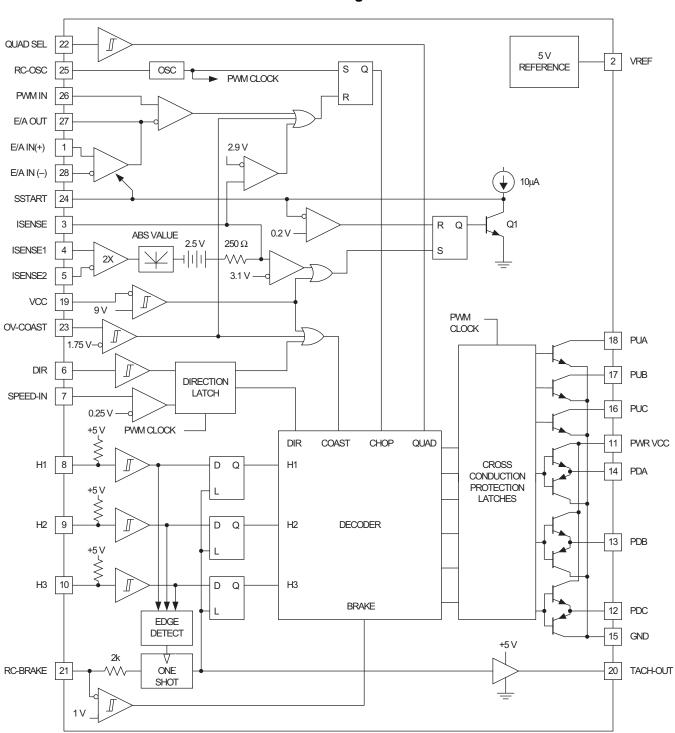
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Threshold to brake, RC-brake		0.8	1.0	1.2	V
Brake hysteresis, RC-brake	55°C to 405°C		0.09	0.4	V
SPEED-IN threshold	-55°C to 125°C	220	257	290	mV
SPEED-IN input current		-30	– 5	30	μA
Low-Side Drivers ⁽¹⁾				.	
Voh, -1 mA, down from V _{CC}			1.60	2.50	
Voh, –50 mA, down from V _{CC}	55°0 to 405°0		1.75	2.45	
Vol, 1 mA	-55°C to 125°C		0.05	0.4	V
Vol, 50 mA			0.36	0.9	
Rise/fall time	10% to 90% slew time, into 1 nF		50	500	ns
High-Side Drivers	,			,	
Vol, 1 mA	5500 + 40500		0.1	0.4	.,
Vol, 50 mA	-55°C to 125°C		1.0	1.8	V
Leakage current	Output voltage = 50 V			30	μA
Fall time	10% to 90% slew time, 50 mA load		50		ns
Oscillator		·		.	
Frequency	-55°C to 125°C	30		80	kHz
Reference		<u> </u>		'	
Output walks as	Iref = 0 mA, 25°C	4.85	5.0	5.15	
Output voltage	-55°C to 125°C	4.7	5.0	5.3	V
Load regulation	0 mA to -20 mA load	-40	- 5		
Line regulation	10 V to 18 V V _{CC}	-10	-1	10	mV
Short circuit current	-55°C to 125°C	20	100	150	mA
Miscellaneous					
Output turn-on delay			1		
Output turn-off delay			1		μs

⁽¹⁾ Current available from these pins can peak as high as 0.5 A.

Copyright © 2011, Texas Instruments Incorporated



Block Diagram





DEVICE INFORMATION

Terminal Functions

TERMINAL NO		DESCRIPTION				
NAME	NO.	DESCRIPTION				
DIR, SPEED-IN	6, 7	The position decoder logic translates the Hall signals and the DIR signal to the correct driver signals (PUs and PDs). To prevent output stage damage, the signal on DIR is first loaded into a direction latch, then shifted through a two-bit register. As long as SPEED-IN is less than 250 mV, the direction latch is transparent. When SPEED-IN is higher than 250 mV, the direction latch inhibits all changes indirection. SPEED-IN can be connected to TACH-OUT through a filter, so that the direction latch is only transparent when the motor is spinning slowly, and has too little stored energy to damage power devices. Additional circuitry detects when the input and output of the direction latch are different, or when the input and output of the shift register are different, and inhibits all output drives during that time. This can be used to allow the motor to coast to a safe speed before reversing. The shift register ensures that direction can not be changed instantaneously. The register is clocked by the PWM oscillator, so the delay between direction changes is always going to be between one and two oscillator periods. At 40 kHz, this corresponds to a delay of between 25 µs and 50 µs. Regardless of output stage, 25 µs deadtime should be adequate to ensure no overlap cross-conduction. Toggling DIR causes an output pulse on TACH-OUT regardless of motor speed.				
E/A IN(+), E/A IN(-), E/A OUT, PWM IN	1, 28, 27, 26	E/A IN(+) and E/A IN(-) are not internally committed to allow for a wide variety of uses. They can be connected to the ISENSE, to TACH-OUT through a filter, to an external command voltage, to a D/A converter for computer control, or to another op amp for more elegant feedback loops. The error amplifier is compensated for unity gain stability, so E/A OUT can be tied to E/A IN(-) for feedback and major loop compensation. E/A OUT and PWM In drive the PWM comparator. For voltage-mode PWM systems, PWM In can be connected to RC-OSC. The PWM comparator clears the PWM latch, commanding the outputs to chop. The error amplifier can be biased off by connecting E/A IN(-) to a higher voltage than /EA IN(+). When biased off, E/A OUT appears to the application as a resistor to ground. E/A OUT can then be driven by an external amplifier.				
GND	15	All thresholds and outputs are referred to the GND pin except for the PD and PU outputs.				
H1, H2, H3	8, 9, 10	The three shaft position sensor inputs consist of hysteresis comparators with input pullup resistors. Logic thresholds meet TTL specifications and can be driven by 5-V CMOS, 12-V CMOS, NMOS, or open-collectors. Connect these inputs to motor shaft position sensors that are positioned 120 electrical degrees apart. If noisy signals are expected, zener clamp and filter these inputs with 6-V zeners and an RC filter. Suggested filtering components are 1 k Ω and 2 nF. Edge skew in the filter is not a problem, because sensors normally generate modified gray code with only one output changing at a time, but rise and fall times must be shorter than 20 μ s for correct tachometer operation. Motors with 60 electrical degree position sensor coding can be used if one or two of the position sensor signals is inverted.				
ISENSE1, ISENSE2, ISENSE	3, 4, 5	The current sense amplifier has a fixed gain of approximately two. It also has a built-in level shift of approximately 2.5 V. The signal appearing on ISENSE is: $I_{SENSE} = 2.5 \text{ V} + (2 \times \text{ABS} \text{ (}I_{SENSE1} - I_{SENSE2})\text{)}$ $I_{SENSE1} \text{ and }I_{SENSE2} \text{ are interchangeable and can be used as differential inputs. The differential signal applied can be as high as \pm 0.5 \text{ V} before saturation. If spikes are expected on ISENSE1 or ISENSE2, they are best filtered by a capacitor from ISENSE to ground. Filtering this way allows fast signal inversions to be correctly processed by the absolute value circuit. The peak-current comparator allows the PWM to enter a current-limit mode with current in the windings never exceeding approximately 0.2 V / R_{SENSE}. The overcurrent comparator provides a fail-safe shutdown in the unlikely case of current exceeding 0.3 V / R_{SENSE}. Then, softstart is commanded, and all outputs are turned off until the high current condition is removed. It is often essential to use some filter driving ISENSE1 and ISENSE2 to reject extreme spikes and to control slew rate. Reasonable starting values for filter components might be 250 \cdot \Omega series resistors and a 5-nF capacitor between ISENSE1 and ISENSE2. Input resistors should be kept small and matched to maintain gain accuracy.$				
OV-COAST	23	This input can be used as an over-voltage shut-down input, as a coast input, or both. This input can be driven by TTL, 5-V CMOS, or 12-V CMOS.				

Submit Documentation Feedback Copyright © 2011, Texas Instruments Incorporated



Terminal Functions (continued)

TERMINAL TERMINAL									
NAME	NO.	DESCRIPTION							
PDA, PDB, PDC	12, 13, 14	These outputs can drive the gates of N-channel power MOSFETs directly or they can drive the bases of power Darlingtons if some form of current limiting is used. They are meant to drive low-side power devices in high-current output stages. Current available from these pins can peak as high as 0.5 A. These outputs feature a true totem-pole output stage. Beware of exceeding device power dissipation limits when using these outputs for high continuous currents. These outputs pull high to turn a "low-side" device on (active high).							
PUA, PUB, PUC	16, 17, 18	These outputs are open-collector, high-voltage drivers that are meant to drive high-side power devices in high-current output stages. These are active low outputs, meaning that these outputs pull low to command a high-side device on. These outputs can drive low-voltage PNP Darlingtons and P-channel MOSFETs directly, and can drive any high-voltage device using external charge pump techniques, transformer signal coupling, cascode level-shift transistors, or opto-isolated drive (high-speed opto devices are recommended). (See applications).							
PWR VCC	11	This supply pin carries the current sourced by the PD outputs. When connecting PD outputs directly to the bases of power Darlingtons, the PWR VCC pin can be current limited with a resistor. Darlington outputs can also be "Baker Clamped" with diodes from collectors back to PWR VCC. (See Applications)							
QUAD SEL	22	The device can chop power devices in either of two modes, referred to as "two-quadrant" (Quad Sellow) and "four quadrant" (Quad Sel high). When two-quadrant chopping, the pulldown power devices are chopped by the output of the PWM latch while the pullup drivers remain on. The load chops into one commutation diode, and except for back-EMF, will exhibit slow discharge current and faster charge current. Two-quadrant chopping can be more efficient than four-quadrant. When four-quadrant chopping, all power drivers are chopped by the PWM latch, causing the load current to flow into two diodes during chopping. This mode exhibits better control of load current when current is low, and is preferred in servo systems for equal control over acceleration and deceleration. The QUAD SEL input has no effect on operation during braking.							
RC-BRAKE	21	Each time the TACH-OUT pulses, the capacitor tied to RC-BRAKE discharges from approximately 3.33 V down to 1.67 V through a resistor. The tachometer pulse width is approximately T = 0.67 R_T C_T , where R_T and C_T are a resistor and capacitor from RC-BRAKE to ground. Recommended values for R_T are 10 k Ω to 500 k Ω , and recommended values for C_T are 1 nF to 100 nF, allowing times between 5 μ s and 10 ms. Best accuracy and stability are achieved with values in the centers of those ranges. RC-BRAKE also has another function. If RC-BRAKE pin is pulled below the brake threshold, the device enters brake mode. This mode consists of turning off all three high-side devices, enabling all three low-side devices, and disabling the tachometer. The only things that inhibit low-side device operation in braking are low-supply, exceeding peak current, OV-COAST command, and the PWM comparator signal. The last of these means that if current sense is implemented such that the signal in the current sense amplifier is proportional to braking current, the low-side devices will brake the motor with current control. (See applications) Simpler current sense connections results in uncontrolled braking and potential damage to the power devices.							
RC-OSC	25	The UC1625 can regulate motor current using fixed-frequency pulse width modulation (PWM). The RC-OSC pin sets oscillator frequency by means of timing resistor R_{OSC} from the RC-OSC pin to VREF and capacitor COSC from RC-OSC to Gnd. Resistors 10 k Ω to 100 k Ω and capacitors 1 nF to 100 nF works the best, but frequency should always be below 500 kHz. Oscillator frequency is approximately: $F = 2/(R_{OSC} \times C_{OSC})$ Additional components can be added to this device to cause it to operate as a fixed off-time PWM rather than a fixed frequency PWM, using the RC-OSC pin to select the monostable time constant. The voltage on the RC-OSC pin is normally a ramp of about 1.2 V peak-to-peak, centered at approximately 1.6 V. This ramp can be used for voltage-mode PWM control, or can be used for slope compensation in current-mode control.							



Terminal Functions (continued)

TERMINAL		DECORPORTION
NAME	NO.	DESCRIPTION
SSTART	24	Any time that VCC drops below threshold or the sensed current exceeds the over-current threshold, the soft-start latch is set. When set, it turns on a transistor that pulls down on SSTART. Normally, a capacitor is connected to this pin, and the transistor will completely discharge the capacitor. A comparator senses when the NPN transistor has completely discharged the capacitor, and allows the soft-start latch to clear when the fault is removed. When the fault is removed, the soft-start capacitor charges from the on-chip current source. SSTART clamps the output of the error amplifier, not allowing the error amplifier output voltage to exceed SSTART regardless of input. The ramp on RC-OSC can be applied to PWM In and compared to E/A OUT. With SSTART discharged below 0.2 V and the ramp minimum being approximately 1.0 V, the PWM comparator keeps the PWM latch cleared and the outputs off. As SSTART rises, the PWM comparator begins to duty-cycle modulate the PWM latch until the error amplifier inputs overcome the clamp. This provides for a safe and orderly motor start-up from an off or fault condition. A 51-k Ω resister is added between VREF and SSTART to ensure switching.
TACH-OUT	20	Any change in the H1, H2, or H3 inputs loads data from these inputs into the position sensor latches. At the same time data is loaded, a fixed-width 5-V pulse is triggered on TACH-OUT. The average value of the voltage on TACH-OUT is directly proportional to speed, so this output can be used as a true tachometer for speed feedback with an external filter or averaging circuit which usually consists of a resistor and capacitor. Whenever TACH-OUT is high, the position latches are inhibited, such that during the noisiest part of the commutation cycle, additional commutations are not possible. Although this effectively sets a maximum rotational speed, the maximum speed can be set above the highest expected speed, preventing false commutation and chatter.
vcc	19	This device operates with supplies between 10 V and 18 V. Under-voltage lockout keeps all outputs off below 7.5 V, insuring that the output transistors never turn on until full drive capability is available. Bypass VCC to ground with an 0.1-µF ceramic capacitor. Using a 10-µF electrolytic bypass capacitor as well can be beneficial in applications with high supply impedance.
VREF	2	This pin provides regulated 5 V for driving Hall-effect devices and speed control circuitry. VREF reaches 5 V before VCC enables, ensuring that Hall-effect devices powered from VREF becomes active before the UC1625 drives any output. For proper performance VREF should be bypassed with at least a 0.1-µF capacitor to ground.

TYPICAL CHARACTERISTICS

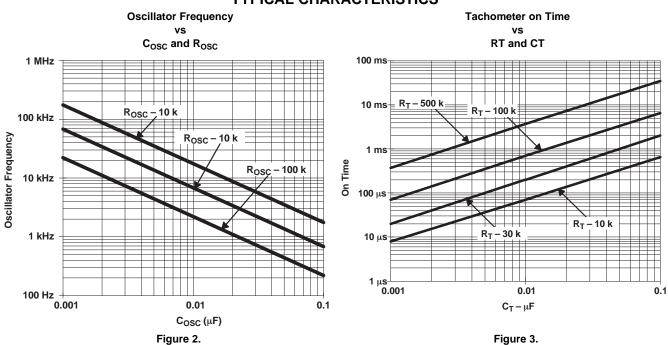
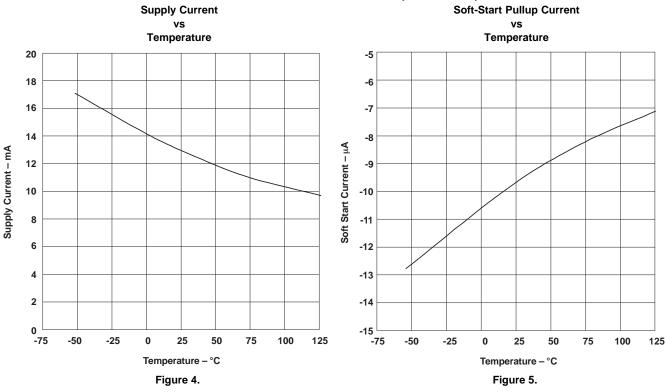


Figure 3.



TYPICAL CHARACTERISTICS (continued)



Soft-Start Discharge Current

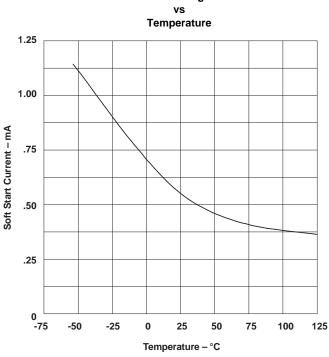


Figure 6.

Current Sense Amplifier Transfer Function

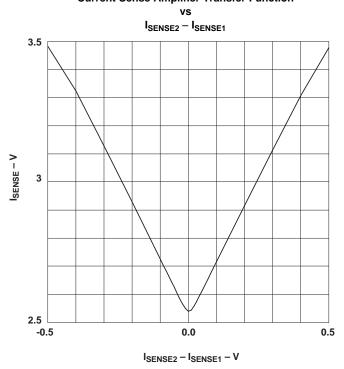


Figure 7.



APPLICATION INFORMATION

Cross Conduction Prevention

The UC1625 inserts delays to prevent cross conduction due to overlapping drive signals. However, some thought must always be given to cross conduction in output stage design because no amount of dead time can prevent fast slewing signals from coupling drive to a power device through a parasitic capacitance.

The UC1625 contains input latches that serve as noise blanking filters. These latches remain transparent through any phase of a motor rotation and latch immediately after an input transition is detected. They remain latched for two cycles of the PWM oscillator. At a PWM oscillator speed of 20 kHz, this corresponds to 50 μ s to 100 μ s of blank time which limits maximum rotational speed to 100 kRPM for a motor with six transitions per rotation or 50 kRPM for a motor with 12 transitions per rotation.

This prevents noise generated in the first 50 µs of a transition from propagating to the output transistors and causing cross-conduction or chatter.

The UC1625 also contains six flip flops corresponding to the six output drive signals. One of these flip flops is set every time that an output drive signal is turned on, and cleared two PWM oscillator cycles after that drive signal is turned off. The output of each flip flop is used to inhibit drive to the opposing output (Figure 8). In this way, it is impossible to turn on driver PUA and PDA at the same time. It is also impossible for one of these drivers to turn on without the other driver having been off for at least two PWM oscillator clocks.

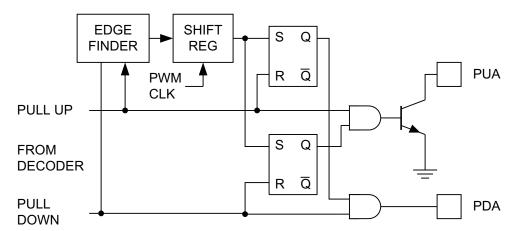


Figure 8. Cross Conduction Prevention

Copyright © 2011, Texas Instruments Incorporated



Power Stage Design

The UC1625 is useful in a wide variety of applications, including high-power in robotics and machinery. The power output stages used in such equipment can take a number of forms, according to the intended performance and purpose of the system. Figure 9 show four different power stages with the advantages and disadvantages of each.

For high-frequency chopping, fast recovery circulating diodes are essential. Six are required to clamp the windings. These diodes should have a continuous current rating at least equal to the operating motor current, since diode conduction duty-cycle can be high. For low-voltage systems, Schottky diodes are preferred. In higher voltage systems, diodes such as Microsemi UHVP high voltage platinum rectifiers are recommended.

In a pulse-by-pulse current control arrangement, current sensing is done by resistor R_S , through which the transistor's currents are passed (Fig. A, B, and C). In these cases, R_D is not needed. The low-side circulating diodes go to ground and the current sense terminals of the UC1625 (I_{SENSE1} and I_{SENSE2}) are connected to R_S through a differential RC filter. The input bias current of the current sense amplifier causes a common mode offset voltage to appear at both inputs, so for best accuracy, keep the filter resistors below 2 k Ω and matched.

The current that flows through R_S is discontinuous because of chopping. It flows during the on time of the power stage and is zero during the off time. Consequently, the voltage across R_S consists of a series of pulses, occurring at the PWM frequency, with a peak value indicative of the peak motor current.

To sense average motor current instead of peak current, add another current sense resistor (R_D in Fig. D) to measure current in the low-side circulating diodes, and operate in four quadrant mode (pin 22 high). The negative voltage across R_D is corrected by the absolute value current sense amplifier. Within the limitations imposed by Table 2, the circuit of Fig. B can also sense average current.



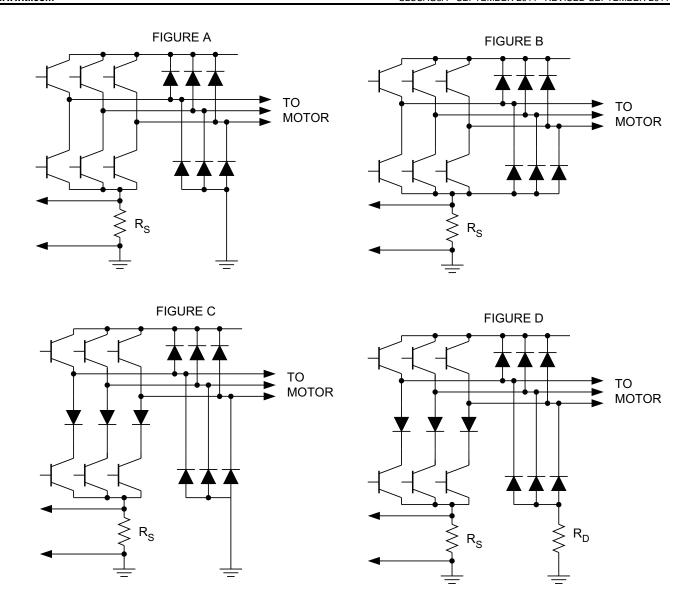


Figure 9. Four Power Stage Designs

Table 2. Imposed Limitations for Figure 9

	2 QUADRANT	DRANT 4 QUADRANT SAFE		POWER REVERSE	CURRENT SENSE		
	2 QUADRANT	4 QUADRANI	BRAKING	POWER REVERSE	Pulse-by-Pulse	Average	
Figure A	Yes	No	No	N0	Yes	No	
Figure B	Yes	Yes	No	In 4-quad mode only	Yes	Yes	
Figure C	Yes	Yes	Yes	In 4-quad mode only	Yes	No	
Figure D	Yes	Yes	Yes	In 4-quad mode only	Yes	Yes	

Copyright © 2011, Texas Instruments Incorporated



For drives where speed is critical, P-channel MOSFETs can be driven by emitter followers as shown in Figure 10. Here, both the level shift NPN and the PNP must withstand high voltages. A zener diode is used to limit gate-source voltage on the MOSFET. A series gate resistor is not necessary, but always advisable to control overshoot and ringing.

High-voltage optocouplers can quickly drive high-voltage MOSFETs if a boost supply of at least 10 V greater than the motor supply is provided (See Figure 11) To protect the MOSFET, the boost supply should not be higher than 18 V above the motor supply.

For under 200-V 2-quadrant applications, a power NPN driven by a small P-Channel MOSFET performs well as a high-side driver as in Figure 12. A high voltage small-signal NPN is used as a level shift and a high voltage low-current MOSFET provides drive. Although the NPN does not saturate if used within its limitations, the base-emitter resistor on the NPN is still the speed-limiting component.

Figure 13 shows a power NPN Darlington drive technique using a clamp to prevent deep saturation. By limiting saturation of the power device, excessive base drive is minimized and turn-off time is kept fairly short. Lack of base series resistance also adds to the speed of this approach.

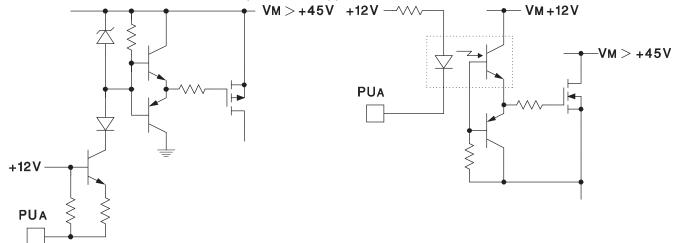


Figure 10. Fast High-Side P-Channel Driver

Figure 11. Optocoupled N-Channel High-Side



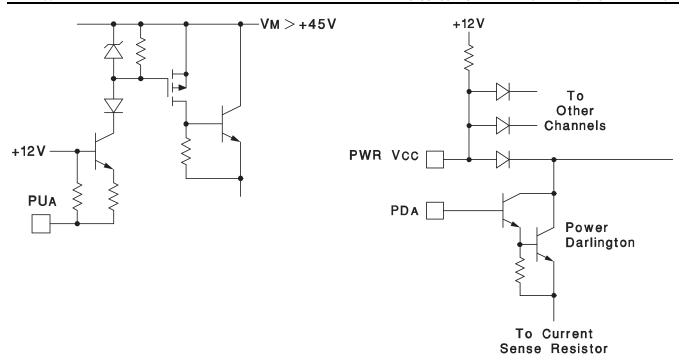


Figure 12. Power NPN High-Side Driver

Figure 13. Power NPN Low-Side Driver



Fast High-Side N-Channel Driver with Transformer Isolation

A small pulse transformer can provide excellent isolation between the UC1625 and a high-voltage N-Channel MOSFET while also coupling gate drive power. In this circuit (shown in Figure 14), a UC3724 is used as a transformer driver/encoder that duty-cycle modulates the transformer with a 150-kHz pulse train. The UC3725 rectifies this pulse train for gate drive power, demodulates the signal, and drives the gate with over 2-A peak current.

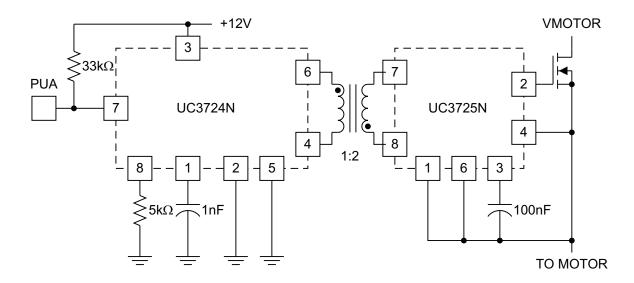


Figure 14. Fast High-Side N-Channel Driver with Transformer Isolation

Both the UC3724 and the UC3725 can operate up to 500 kHz if the pulse transformer is selected appropriately. To raise the operating frequency, either lower the timing resistor of the UC3724 (1 k Ω min), lower the timing capacitor of the UC3724 (500 pF min) or both.

If there is significant capacitance between transformer primary and secondary, together with very high output slew rate, then it may be necessary to add clamp diodes from the transformer primary to 12 V and ground. General purpose small signal switching diodes such as 1N4148 are normally adequate.

The UC3725 also has provisions for MOSFET current limiting. See the UC3725 data sheet for more information on implementing this.



Computational Truth Table

Table 3 shows the outputs of the gate drive and open collector outputs for given hall input codes and direction signals. Numbers at the top of the columns are pin numbers.

These devices operate with position sensor encoding that has either one or two signals high at a time, never all low or all high. This coding is sometimes referred to as "120° Coding" because the coding is the same as coding with position sensors spaced 120 magnetic degrees about the rotor. In response to these position sense signals, only one low-side driver turns on (go high) and one high-side driver turns on (pull low) at any time.

Table 3. Computational Truth Table

	INP	UTS		OUTPUTS						
DIR	H1	H2	Н3		Low-Side High-Side					
6	8	9	10	12	13	14	16	17	18	
1	0	0	1	L	Н	L	L	Н	Н	
1	0	1	1	L	L	Н	L	Н	Н	
1	0	1	0	L	L	Н	Н	L	Н	
1	1	1	0	Н	L	L	Н	L	Н	
1	1	0	0	Н	L	L	Н	Н	L	
1	1	0	1	L	Н	L	Н	Н	L	
0	1	0	1	L	L	Н	Н	L	Н	
0	1	0	0	L	L	Н	L	Н	Н	
0	1	1	0	L	Н	L	L	Н	Н	
0	0	1	0	L	Н	L	Н	Н	L	
0	0	1	1	Н	L	L	Н	Н	L	
0	0	0	1	Н	L	L	Н	L	Н	
Х	1	1	1	L	L	L	Н	Н	Н	
Х	0	0	0	L	L	L	Н	Н	Н	



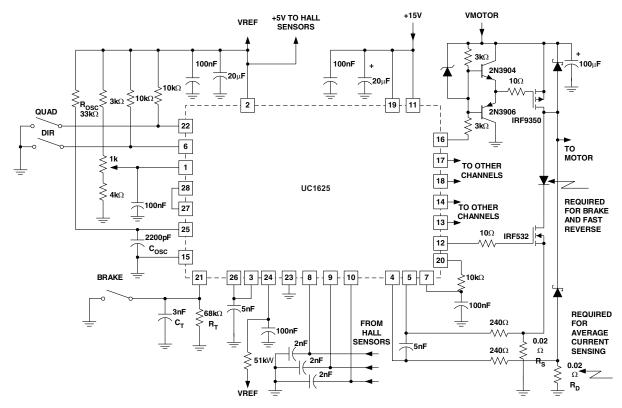


Figure 15. 45-V/8-A Brushless DC Motor Drive Circuit

N-Channel power MOSFETs are used for low-side drivers, while P-Channel power MOSFETs are shown for high-side drivers. Resistors are used to level shift the UC1625 open-collector outputs, driving emitter followers into the MOSFET gate. A 12-V zener clamp insures that the MOSFET gate-source voltage never exceeds 12 V. Series $10-\Omega$ gate resistors tame gate reactance, preventing oscillations and minimizing ringing.

The oscillator timing capacitor should be placed close to pins 15 and 25, to keep ground current out of the capacitor. Ground current in the timing capacitor causes oscillator distortion and slaving to the commutation signal.

The potentiometer connected to pin 1 controls PWM duty cycle directly, implementing a crude form of speed control. This control is often referred to as "voltage mode" because the potentiometer position sets the average motor voltage. This controls speed because steady-state motor speed is closely related to applied voltage.

Pin 20 (Tach-Out) is connected to pin 7 (SPEED IN) through an RC filter, preventing direction reversal while the motor is spinning quickly. In two-quadrant operation, this reversal can cause kinetic energy from the motor to be forced into the power MOSFETs.

A diode in series with the low-side MOSFETs facilitates PWM current control during braking by insuring that braking current will not flow backwards through low-side MOSFETs. Dual current-sense resistors give continuous current sense, whether braking or running in four-quadrant operation, an unnecessary luxury for two-quadrant operation.

The $68-k\Omega$ and 3-nF tachometer components set maximum commutation time at 140 μ s. This permits smooth operation up to 35,000 RPM for four-pole motors, yet gives 140 μ s of noise blanking after commutation.



PACKAGE OPTION ADDENDUM

13-Mar-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
5962-9168902VYA	ACTIVE	CDIP SB	JDJ	28	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9168902VY A UC1625-SP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

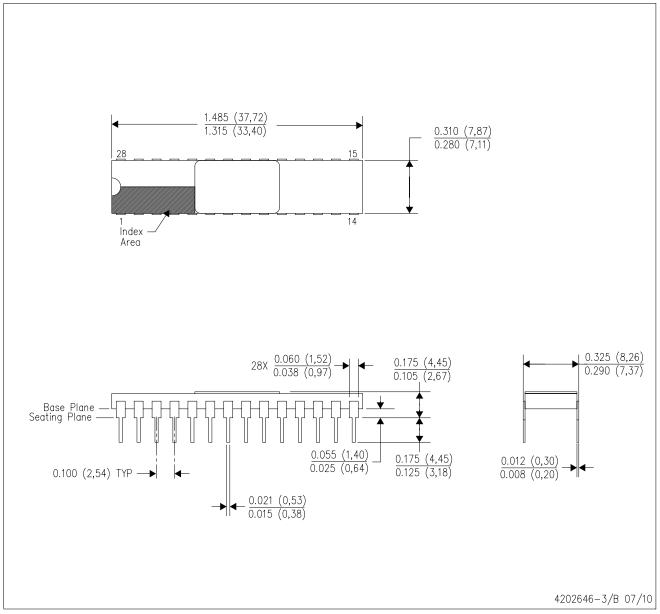
- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

JDJ (R-CDIP-T28)

CERAMIC DUAL IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Ceramic quad flatpack with flat leads brazed to non-conductive tie bar carrier.
- D. This package is hermetically sealed with a metal lid.
- E. The leads are gold plated and can be solderdipped.
- F. Leads not shown for clarity purposes.
- G. Lid and heat sink are connected to GND leads.



IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.